

Trade Media Release

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GF receives OCP Inspired™ recognition for industry-first PVDF in-rack manifold

GF's PVDF-based in-rack manifold for direct-to-chip liquid cooling has received OCP Inspired™ recognition, marking an important milestone for the adoption of advanced polymer technologies in next-generation data center cooling infrastructure. The solution is the first polymer-based manifold to receive this recognition within the Open Compute Project (OCP) Inspired™ program.

As part of the OCP ecosystem, GF contributes engineered polymer piping systems and hydronic infrastructure solutions designed for direct-to-chip liquid cooling (DLC) applications in hyperscale and AI data centers. GF's LiquidCore portfolio combines piping, valves, instrumentation, hydronic specialties, engineering expertise, jointing technologies, and pre-fabrication to support reliable and efficient coolant distribution from the facility water system through the technology cooling system and on to the chip via cold plate.

The newly recognized OCP Inspired™ in-rack manifold is based on GF's long-proven SYGEF PVDF material platform and was developed to support demanding thermal management environments where coolant purity, corrosion resistance, and long-term reliability are critical. Unlike conventional metallic manifolds, the solution utilizes a polymer design engineered to support uniform flow distribution across all outlet ports, helping maintain stable and repeatable cooling performance throughout the rack. The lightweight PVDF construction also enables corrosion-free operation and simplified integration through flexible connection and mounting options.

Each manifold is custom-engineered according to client-specific rack and cooling requirements and undergoes a 100% pressure test with water before delivery to ensure maximum reliability and safety. The manifold concept has already been validated through multiple proof-of-concept deployments and live data center installations across the Americas, Europe and Asia-Pacific.

Building on decades of experience in mission-critical applications and ultra-pure water systems for semiconductor manufacturing, GF is pioneering the use of engineered polymers in next-generation data center cooling. The company has long supported leading chip manufacturers and high-tech industries worldwide with reliable flow solutions designed for highly demanding operating environments.

"OCP plays a key role in driving collaboration and standardization across the data center industry," said Charles Freda, Global Head Data Centers at GF. "Receiving OCP Inspired™ recognition for our PVDF in-rack manifold reflects both the maturity of advanced polymer flow solutions and our commitment to supporting open and interoperable liquid cooling ecosystems for high-performance computing."

Direct liquid cooling is rapidly becoming the preferred cooling approach for AI and high-density computing environments, where rack densities increasingly exceed 100 kW. In these systems, the quality and reliability of the hydronic infrastructure are essential to maintaining thermal performance and protecting sensitive cold plate technologies. GF's engineered polymer piping systems are specifically designed to address these requirements through corrosion-free operation, smooth internal surfaces, and contamination-minimized jointing technologies.

The OCP ecosystem increasingly supports interoperable and multi-vendor liquid cooling infrastructures through standardized interfaces and validated material approaches. Industry guidance for liquid cooling systems today recognizes several advanced polymers as suitable wetted materials, supporting the broader adoption of high-performance polymer technologies in next-generation data center cooling applications.

Learn more about polymer solutions for direct-to-chip liquid cooling: gfps.com/liquidcore

For further information please contact

Franciska Janzon
Head Corporate Reporting and Media Relations
Global Communications
Phone +358401921653
franciska.janzon@georgfischer.com

Corporate Profile

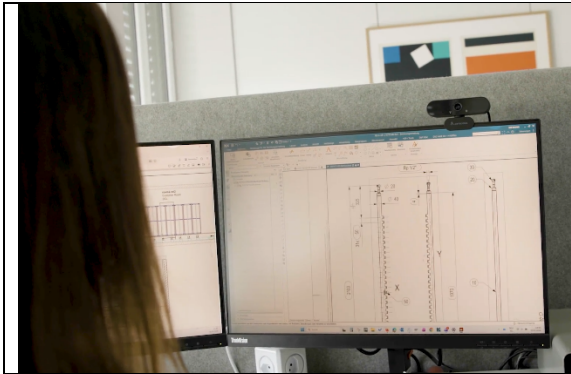
With a rich history in industrial innovation since 1802, GF is reshaping the future of Flow Solutions by delivering Excellence in Flow through mission-critical products and solutions that enable the safe and sustainable transport of water and other fluids for Buildings, Industry and Infrastructure. Headquartered in Switzerland, GF employs about 13'300 professionals across 46 countries. In 2025 GF's Flow Solutions business generated sales of CHF 3 billion. GF is listed on the SIX Swiss Exchange.

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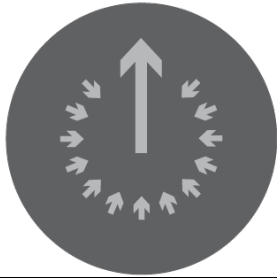
Pictures

	<p>GF's PVDF-based in-rack manifold for direct-to-chip liquid cooling has received OCP Inspired™ recognition, highlighting the growing adoption of advanced polymer materials as wetted components in next-generation liquid cooling infrastructure.</p> <p>Source: GF</p>
	<p>The PVDF in-rack manifold support uniform flow distribution, corrosion-free operation, lightweight construction, and flexible integration into high-density AI data center environments.</p> <p>Source: GF</p>



GF's engineering experts design each manifold according to customer-specific rack layouts and cooling requirements, ensuring optimized flow performance, seamless integration, and reliable operation across the entire cooling loop.

Source: GF



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